



**Product Change Notification / RMES-09XJN386**

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**Date:**

24-Jun-2022

**Product Category:**

Power MOSFET Drivers, Switching Regulators

**PCN Type:**

Manufacturing Change

**Notification Subject:**

CCB 4771 Final Notice: Qualification of MTAI as a new assembly site for Microsemi SG3526DW, SG3526BDW, SG2526BDW, SG2803DW and SG2526DW device families available in 18L SOIC (.300in) package.

**Affected CPNs:**

[RMES-09XJN386\\_Affected\\_CPN\\_06242022.pdf](#)

[RMES-09XJN386\\_Affected\\_CPN\\_06242022.csv](#)

**Notification Text:**

**PCN Status:**Final Notification

**PCN Type:**Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of MTAI as a new assembly site for Microsemi SG3526DW, SG3526BDW, SG2526BDW, SG2803DW and SG2526DW device families available in 18L SOIC (.300in) package.

**Pre and Post Change Summary:**

	Pre Change	Post Change
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<b>Assembly Site</b>	UTAC Thai Limited (UTL-1) LTD. (NSEB)	Microchip Technology Thailand (HQ) (MTAI)
<b>Wire material</b>	Au	Au
<b>Die attach material</b>	8200T	8390A
<b>Molding compound material</b>	G605L	G600V
<b>Lead frame material*</b>	A194	CDA194
<b>Lead frame paddle size</b>	160 x 200 mils	160 x 200 mils
<b>Lead Lock (Locking Hole)</b>	Yes	No
<b>Lead frame comparison</b>	See attachment for pre and post change comparison	

Note: \* C194, A194 or CDA194 Lead frame material are the same, it is just a MCHP internal labelling difference.

**Impacts to Data Sheet:**None

**Change Impact:**None

**Reason for Change:**To improve manufacturability by qualifying MTAI as a new assembly site.

**Change Implementation Status:**In Progress

**Estimated First Ship Date:**July 10, 2022 (date code: 2229)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	August 2021					>	June 2022					July 2022				
Workweek	32	33	34	35	36		23	24	25	26	27	28	29	30	31	32
Initial PCN Issue Date		x														
Qual Report Availability											x					
Final PCN Issue Date											x					
Estimated Implementation Date													x			

**Method to Identify Change:**Traceability code

**Qualification Report:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:** August 10, 2021: Issued initial notification.

June 24, 2022: Issued final notification. Attached the Qualification Report. Updated timetable summary.

Corrected lead frame paddle size from 160x250 mils to 160x200 mils. Provided estimated first ship date to be on July 10, 2022.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## **Attachments:**

[PCN\\_RMES-09XJJN386\\_Qual Report.pdf](#)

[PCN\\_RMES-09XJJN386\\_Pre and Post Change Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

SG3526DW

SG2526DW

SG3526DW-TR

SG3526BDW

SG2526BDW

SG2526BDW-TR

SG3526BDW-TR

SG2803DW